ABSTRACT

Contact-making system for semiconductor wire connections

A contact-making system (100) for wire connections on electronic components in semiconductor connection technology is proposed, which comprises a contact-making device (30) having a capillary tube (35) arranged thereon for guiding a bonding wire (1), and at least one electrode, which is allocated to the head piece (40) of the capillary tube, for producing a spark transfer, by means of which spark transfer a bonding-wire endpiece (1') which projects from the head piece (40) is melted to form a bonding-wire sphere (2).

In order to achieve a bonding-wire sphere (2) which is uniformly shaped and is arranged concentrically with respect to the bonding wire (1) or with respect to the bonding-wire endpiece (1'), at least two or more electrodes are provided which are arranged distributed uniformly on the circumference with respect to the head piece (40) or to the bonding-wire endpiece (1') and are in each case effectively connected to an independent power unit, which is constructed as a current source, it being possible to activate the power units from a single control unit.

(Fig. 1)